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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1938-e-ss

TABLE 3-10: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 5											
280h(2)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
281h(2)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
282h(2)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
283h(2)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
284h(2)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
285h(2)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
286h(2)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
287h(2)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
288h(2)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
289h(2)	WREG	Working Register								0000 0000	uuuu uuuu
28Ah(1, 2)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
28Bh(2)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000
28Ch	—	Unimplemented								—	—
28Dh	—	Unimplemented								—	—
28Eh	—	Unimplemented								—	—
28Fh	—	Unimplemented								—	—
290h	—	Unimplemented								—	—
291h	CCPR1L	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	uuuu uuuu
292h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	uuuu uuuu
293h	CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				0000 0000	0000 0000
294h	PWM1CON	P1RSEN	P1DC<6:0>							0000 0000	0000 0000
295h	CCP1AS	CCP1ASE	CCP1AS2	CCP1AS1	CCP1AS0	PSS1AC<1:0>		PSS1BD<1:0>		0000 0000	0000 0000
296h	PSTR1CON	—	—	—	STR1SYNC	STR1D	STR1C	STR1B	STR1A	---0 0001	---0 0001
297h	—	Unimplemented								—	—
298h	CCPR2L	Capture/Compare/PWM Register 2 (LSB)								xxxx xxxx	uuuu uuuu
299h	CCPR2H	Capture/Compare/PWM Register 2 (MSB)								xxxx xxxx	uuuu uuuu
29Ah	CCP2CON	P2M<1:0>		DC2B<1:0>		CCP2M<3:0>				0000 0000	0000 0000
29Bh	PWM2CON	P2RSEN	P2DC<6:0>							0000 0000	0000 0000
29Ch	CCP2AS	CCP2ASE	CCP2AS2	CCP2AS1	CCP2AS0	PSS2AC<1:0>		PSS2BD<1:0>		0000 0000	0000 0000
29Dh	PSTR2CON	—	—	—	STR2SYNC	STR2D	STR2C	STR2B	STR2A	---0 0001	---0 0001
29Eh	CCPTMRS0	C4TSEL1	C4TSEL0	C3TSEL1	C3TSEL0	C2TSEL1	C2TSEL0	C1TSEL1	C1TSEL0	0000 0000	0000 0000
29Fh	CCPTMRS1	—	—	—	—	—	—	C5TSEL<1:0>		---- --00	---- --00

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<14:8>, whose contents are transferred to the upper byte of the program counter.

2: These registers can be addressed from any bank.

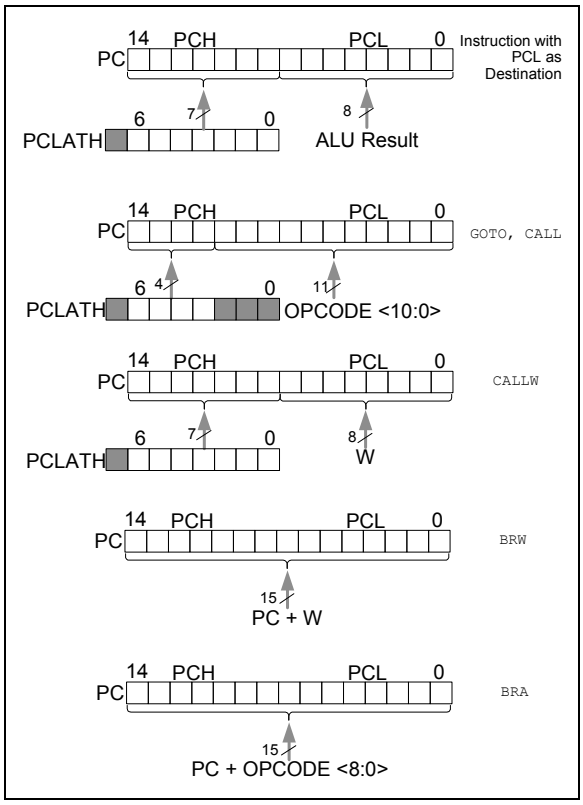
3: These registers/bits are not implemented on PIC16(L)F1938 devices, read as '0'.

4: Unimplemented, read as '1'.

3.4 PCL and PCLATH

The Program Counter (PC) is 15 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<14:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 3-3 shows the five situations for the loading of the PC.

FIGURE 3-3: LOADING OF PC IN DIFFERENT SITUATIONS



3.4.1 MODIFYING PCL

Executing any instruction with the PCL register as the destination simultaneously causes the Program Counter PC<14:8> bits (PCH) to be replaced by the contents of the PCLATH register. This allows the entire contents of the program counter to be changed by writing the desired upper seven bits to the PCLATH register. When the lower eight bits are written to the PCL register, all 15 bits of the program counter will change to the values contained in the PCLATH register and those being written to the PCL register.

3.4.2 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note AN556, *"Implementing a Table Read"* (DS00556).

3.4.3 COMPUTED FUNCTION CALLS

A computed function CALL allows programs to maintain tables of functions and provide another way to execute state machines or look-up tables. When performing a table read using a computed function CALL, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block).

If using the CALL instruction, the PCH<2:0> and PCL registers are loaded with the operand of the CALL instruction. PCH<6:3> is loaded with PCLATH<6:3>.

The CALLW instruction enables computed calls by combining PCLATH and W to form the destination address. A computed CALLW is accomplished by loading the W register with the desired address and executing CALLW. The PCL register is loaded with the value of W and PCH is loaded with PCLATH.

3.4.4 BRANCHING

The branching instructions add an offset to the PC. This allows relocatable code and code that crosses page boundaries. There are two forms of branching, BRW and BRA. The PC will have incremented to fetch the next instruction in both cases. When using either branching instruction, a PCL memory boundary may be crossed.

If using BRW, load the W register with the desired unsigned address and execute BRW. The entire PC will be loaded with the address PC + 1 + W.

If using BRA, the entire PC will be loaded with PC + 1 +, the signed value of the operand of the BRA instruction.

5.3 Clock Switching

The system clock source can be switched between external and internal clock sources via software using the System Clock Select (SCS) bits of the OSCCON register. The following clock sources can be selected using the SCS bits:

- Default system oscillator determined by FOSC bits in Configuration Words
- Timer1 32 kHz crystal oscillator
- Internal Oscillator Block (INTOSC)

5.3.1 SYSTEM CLOCK SELECT (SCS) BITS

The System Clock Select (SCS) bits of the OSCCON register selects the system clock source that is used for the CPU and peripherals.

- When the SCS bits of the OSCCON register = `00`, the system clock source is determined by value of the FOSC<2:0> bits in the Configuration Words.
- When the SCS bits of the OSCCON register = `01`, the system clock source is the Timer1 oscillator.
- When the SCS bits of the OSCCON register = `1x`, the system clock source is chosen by the internal oscillator frequency selected by the IRCF<3:0> bits of the OSCCON register. After a Reset, the SCS bits of the OSCCON register are always cleared.

Note:	Any automatic clock switch, which may occur from Two-Speed Start-up or Fail-Safe Clock Monitor, does not update the SCS bits of the OSCCON register. The user can monitor the OSTS bit of the OSCSTAT register to determine the current system clock source.

When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 5-1.

5.3.2 OSCILLATOR START-UP TIME-OUT STATUS (OSTS) BIT

The Oscillator Start-up Time-out Status (OSTS) bit of the OSCSTAT register indicates whether the system clock is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Words, or from the internal clock source. In particular, OSTS indicates that the Oscillator Start-up Timer (OST) has timed out for LP, XT or HS modes. The OST does not reflect the status of the Timer1 oscillator.

5.3.3 TIMER1 OSCILLATOR

The Timer1 oscillator is a separate crystal oscillator associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSO and T1OSI device pins.

The Timer1 oscillator is enabled using the T1OSCEN control bit in the T1CON register. See **Section 21.0 "Timer1 Module with Gate Control"** for more information about the Timer1 peripheral.

5.3.4 TIMER1 OSCILLATOR READY (T1OSCR) BIT

The user must ensure that the Timer1 Oscillator is ready to be used before it is selected as a system clock source. The Timer1 Oscillator Ready (T1OSCR) bit of the OSCSTAT register indicates whether the Timer1 oscillator is ready to be used. After the T1OSCR bit is set, the SCS bits can be configured to select the Timer1 oscillator.

REGISTER 5-2: OSCSTAT: OSCILLATOR STATUS REGISTER

R-1/q	R-0/q	R-q/q	R-0/q	R-0/q	R-q/q	R-0/q	R-0/q
T1OSCR	PLLR	OSTS	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Conditional

bit 7 **T1OSCR:** Timer1 Oscillator Ready bit
If T1OSCEN = 1:
1 = Timer1 oscillator is ready
0 = Timer1 oscillator is not ready
If T1OSCEN = 0:
1 = Timer1 clock source is always ready

bit 6 **PLLR** 4x PLL Ready bit
1 = 4x PLL is ready
0 = 4x PLL is not ready

bit 5 **OSTS:** Oscillator Start-up Time-out Status bit
1 = Running from the clock defined by the FOSC<2:0> bits of the Configuration Words
0 = Running from an internal oscillator (FOSC<2:0> = 100)

bit 4 **HFIOFR:** High-Frequency Internal Oscillator Ready bit
1 = HFINTOSC is ready
0 = HFINTOSC is not ready

bit 3 **HFIOFL:** High-Frequency Internal Oscillator Locked bit
1 = HFINTOSC is at least 2% accurate
0 = HFINTOSC is not 2% accurate

bit 2 **MFIOFR:** Medium-Frequency Internal Oscillator Ready bit
1 = MFINTOSC is ready
0 = MFINTOSC is not ready

bit 1 **LFIOFR:** Low-Frequency Internal Oscillator Ready bit
1 = LFINTOSC is ready
0 = LFINTOSC is not ready

bit 0 **HFIOFS:** High-Frequency Internal Oscillator Stable bit
1 = HFINTOSC is at least 0.5% accurate
0 = HFINTOSC is not 0.5% accurate

6.11 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON register are updated to indicate the cause of the Reset. Table 6-3 and Table 6-4 show the Reset conditions of these registers.

TABLE 6-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

STKOVF	STKUNF	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	0	1	1	0	x	1	1	Power-on Reset
0	0	1	1	0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	1	1	0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
0	0	1	1	u	0	1	1	Brown-out Reset
u	u	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	0	u	u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	0	u	u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep
u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 6-4: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	---1 1000	00-- 110x
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	---u uuuu	uu-- 0uuu
$\overline{\text{MCLR}}$ Reset during Sleep	0000h	---1 0uuu	uu-- 0uuu
WDT Reset	0000h	---0 uuuu	uu-- uuuu
WDT Wake-up from Sleep	PC + 1	---0 0uuu	uu-- uuuu
Brown-out Reset	0000h	---1 1uuu	00-- 11u0
Interrupt Wake-up from Sleep	PC + 1(1)	---1 0uuu	uu-- uuuu
RESET Instruction Executed	0000h	---u uuuu	uu-- u0uu
Stack Overflow Reset (STVREN = 1)	0000h	---u uuuu	1u-- uuuu
Stack Underflow Reset (STVREN = 1)	0000h	---u uuuu	u1-- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

NOTES:

NOTES:

FIGURE 24-21: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 0)

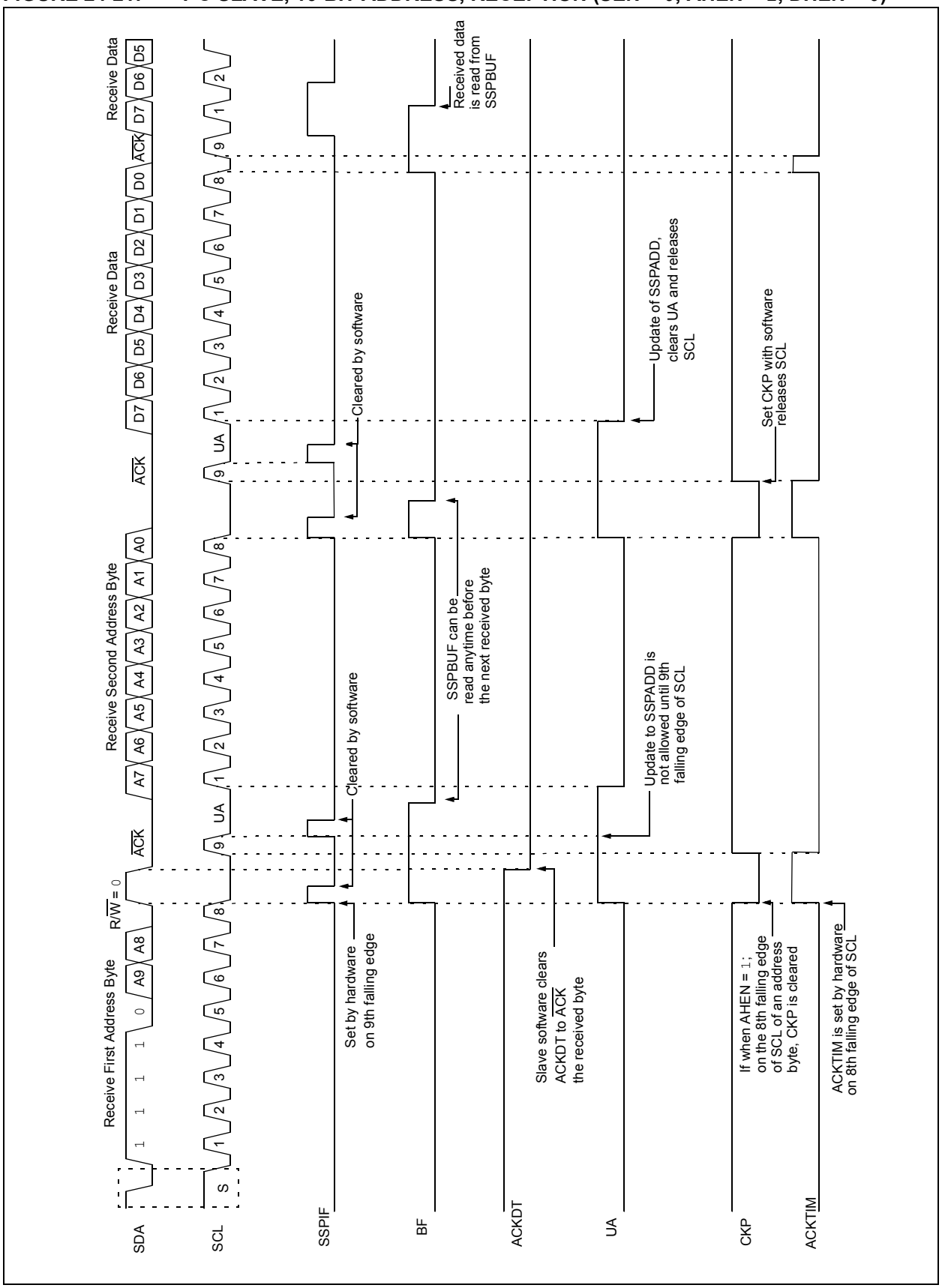


TABLE 25-1: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	298
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	90
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	91
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	94
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	297
SPBRGL	BRG<7:0>								299*
SPBRGH	BRG<15:8>								299*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	134
TXREG	EUSART Transmit Data Register								289*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	296

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for asynchronous transmission.

* Page provides register information.

REGISTER 25-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER(1)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-x/x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RX/DT and TX/CK pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave
Don't care

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enable interrupt and load the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 8-bit (RX9 = 0):
Don't care

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

TABLE 25-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	-0.01	4166	300.0	0.00	3839	300.0	0.00	2303
1200	1200	-0.02	3332	1200	-0.03	1041	1200	0.00	959	1200	0.00	575
2400	2401	-0.04	832	2399	-0.03	520	2400	0.00	479	2400	0.00	287
9600	9615	0.16	207	9615	0.16	129	9600	0.00	119	9600	0.00	71
10417	10417	0.00	191	10417	0.00	119	10378	-0.37	110	10473	0.53	65
19.2k	19.23k	0.16	103	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35
57.6k	57.14k	-0.79	34	56.818	-1.36	21	57.60k	0.00	19	57.60k	0.00	11
115.2k	117.6k	2.12	16	113.636	-1.36	10	115.2k	0.00	9	115.2k	0.00	5

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	299.9	-0.02	1666	300.1	0.04	832	300.0	0.00	767	300.5	0.16	207
1200	1199	-0.08	416	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19.23k	0.16	25	19.23k	0.16	12	19.20k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

25.6 EUSART Operation During Sleep

The EUSART will remain active during Sleep only in the Synchronous Slave mode. All other modes require the system clock and therefore cannot generate the necessary signals to run the Transmit or Receive Shift registers during Sleep.

Synchronous Slave mode uses an externally generated clock to run the Transmit and Receive Shift registers.

25.6.1 SYNCHRONOUS RECEIVE DURING SLEEP

To receive during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for Synchronous Slave Reception (see **Section 25.5.2.4 "Synchronous Slave Reception Set-up:"**).
- If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
- The RCIF interrupt flag must be cleared by reading RCREG to unload any pending characters in the receive buffer.

Upon entering Sleep mode, the device will be ready to accept data and clocks on the RX/DT and TX/CK pins, respectively. When the data word has been completely clocked in by the external device, the RCIF interrupt flag bit of the PIR1 register will be set. Thereby, waking the processor from Sleep.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the GIE global interrupt enable bit of the INTCON register is also set, then the Interrupt Service Routine at address 004h will be called.

25.6.2 SYNCHRONOUS TRANSMIT DURING SLEEP

To transmit during Sleep, all the following conditions must be met before entering Sleep mode:

- RCSTA and TXSTA Control registers must be configured for Synchronous Slave Transmission (see **Section 25.5.2.2 "Synchronous Slave Transmission Set-up:"**).
- The TXIF interrupt flag must be cleared by writing the output data to the TXREG, thereby filling the TSR and transmit buffer.
- If interrupts are desired, set the TXIE bit of the PIE1 register and the PEIE bit of the INTCON register.
- Interrupt enable bits TXIE of the PIE1 register and PEIE of the INTCON register must set.

Upon entering Sleep mode, the device will be ready to accept clocks on TX/CK pin and transmit data on the RX/DT pin. When the data word in the TSR has been completely clocked out by the external device, the pending byte in the TXREG will transfer to the TSR and the TXIF flag will be set. Thereby, waking the processor from Sleep. At this point, the TXREG is available to accept another character for transmission, which will clear the TXIF flag.

Upon waking from Sleep, the instruction following the SLEEP instruction will be executed. If the Global Interrupt Enable (GIE) bit is also set then the Interrupt Service Routine at address 0004h will be called.

26.4 Current Ranges

The capacitive sensing oscillator can operate within several different current ranges, depending on the voltage reference mode and current range selections. Within each of the two voltage reference modes there are four current ranges.

Selection between the voltage reference modes is controlled by the CPSRM bit of the CPSCON0 register. Clearing this bit selects the fixed voltage references provided by the capacitive sensing oscillator module. Setting this bit selects the variable voltage references supplied by the Fixed Voltage reference (FVR) module and the Digital-to-Analog Converter (DAC) module. See **Section 26.3 "Voltage Reference Modes"** for more information on configuring the voltage references.

Selecting the current range within each voltage reference mode is controlled by configuring the CPSRNG<1:0> bits in the CPSCON0 register. See Table 26-1 for proper current mode selection.

The Noise Detection mode is unique in that it disables the constant current source associated with the selected input pin, but leaves the rest of the oscillator circuitry and pin structure active. This eliminates the oscillation frequency on the analog pin and greatly reduces the current consumed by the oscillator module.

When noise is introduced onto the pin, the oscillator is driven at the frequency determined by the noise. This produces a detectable signal at the comparator stage, indicating the presence of activity on the pin.

Figure 26-2 shows a more detailed drawing of the constant current sources and comparators associated with the oscillator and input pin.

TABLE 26-1: CURRENT RANGE SELECTION

CPSRM	Voltage Reference Mode	CPSRNG<1:0>	Current Range(1)
0	Fixed	00	Off
		01	Low
		10	Medium
		11	High
1	Variable	00	Noise Detection
		01	Low
		10	Medium
		11	High

Note 1: See Power-Down Currents (IPD) in **Section 30.0 "Electrical Specifications"** for more information.

NOTES:

27.12 Operation During Sleep

The LCD module can operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Setting the SLPEN bit allows the LCD module to go to Sleep. Clearing the SLPEN bit allows the module to continue to operate during Sleep.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will cease all functions and go into a very low-current consumption mode. The module will stop operation immediately and drive the minimum LCD voltage on both segment and common lines. Figure 27-20 shows this operation.

The LCD module can be configured to operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Clearing SLPEN and correctly configuring the LCD module clock will allow the LCD module to operate during Sleep. Setting SLPEN and correctly executing the LCD module shutdown will disable the LCD module during Sleep and save power.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will immediately cease all functions, drive the outputs to Vss and go into a very low-current mode. The SLEEP instruction should only be executed after the LCD module has been disabled and the current cycle completed, thus ensuring that there are no DC voltages on the glass. To disable the LCD module, clear the LCDEN bit. The LCD module will complete the disabling process after the current frame, clear the LCDA bit and optionally cause an interrupt.

The steps required to properly enter Sleep with the LCD disabled are:

- Clear LCDEN
- Wait for LCDA = 0 either by polling or by interrupt
- Execute SLEEP

If SLPEN = 0 and SLEEP is executed while the LCD module clock source is FOSC/4, then the LCD module will halt with the pin driving the last LCD voltage pattern. Prolonged exposure to a fixed LCD voltage pattern will cause damage to the LCD glass. To prevent LCD glass damage, either perform the proper LCD module shutdown prior to Sleep, or change the LCD module clock to allow the LCD module to continue operation during Sleep.

If a SLEEP instruction is executed and SLPEN = 0 and the LCD module clock is either T1OSC or LFINTOSC, the module will continue to display the current contents of the LCDDATA registers. While in Sleep, the LCD data cannot be changed. If the LCDIE bit is set, the device will wake from Sleep on the next LCD frame boundary. The LCD module current consumption will not decrease in this mode; however, the overall device power consumption will be lower due to the shutdown of the CPU and other peripherals.

Table 27-8 shows the status of the LCD module during a Sleep while using each of the three available clock sources.

Note:	When the LCDEN bit is cleared, the LCD module will be disabled at the completion of frame. At this time, the port pins will revert to digital functionality. To minimize power consumption due to floating digital inputs, the LCD pins should be driven low using the PORT and TRIS registers.

If a SLEEP instruction is executed and SLPEN = 0, the module will continue to display the current contents of the LCDDATA registers. To allow the module to continue operation while in Sleep, the clock source must be either the LFINTOSC or T1OSC external oscillator. While in Sleep, the LCD data cannot be changed. The LCD module current consumption will not decrease in this mode; however, the overall consumption of the device will be lower due to shut down of the core and other peripheral functions.

Table 27-8 shows the status of the LCD module during Sleep while using each of the three available clock sources:

TABLE 27-8: LCD MODULE STATUS DURING SLEEP

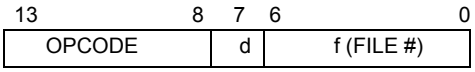
Clock Source	SLPEN	Operational During Sleep
T1OSC	0	Yes
	1	No
LFINTOSC	0	Yes
	1	No
FOSC/4	0	No
	1	No

Note:	The LFINTOSC or external T1OSC oscillator must be used to operate the LCD module during Sleep.

If LCD interrupts are being generated (Type-B waveform with a multiplex mode not static) and LCDIE = 1, the device will awaken from Sleep on the next frame boundary.

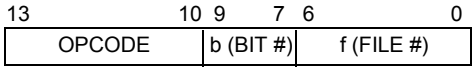
FIGURE 29-1: GENERAL FORMAT FOR INSTRUCTIONS

Byte-oriented file register operations



d = 0 for destination W
d = 1 for destination f
f = 7-bit file register address

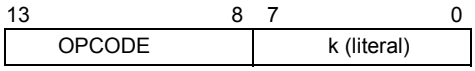
Bit-oriented file register operations



b = 3-bit bit address
f = 7-bit file register address

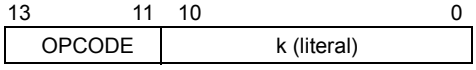
Literal and control operations

General



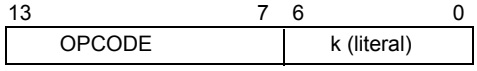
k = 8-bit immediate value

CALL and GOTO instructions only



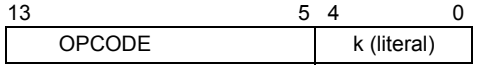
k = 11-bit immediate value

MOVLP instruction only



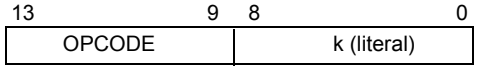
k = 7-bit immediate value

MOVLB instruction only



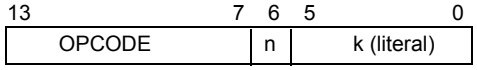
k = 5-bit immediate value

BRA instruction only



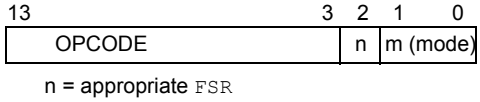
k = 9-bit immediate value

FSR Offset instructions



n = appropriate FSR
k = 6-bit immediate value

FSR Increment instructions



n = appropriate FSR
m = 2-bit mode value

OPCODE only

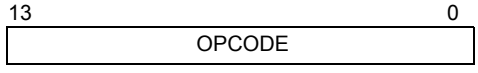


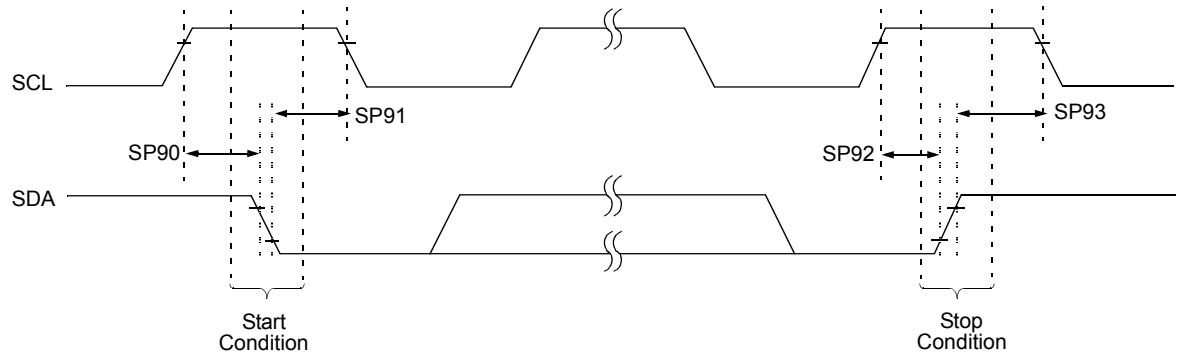
TABLE 30-14: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input		Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDO data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}$↑ to SDO output high-impedance		10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}$↓ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 30-20: I²C™ BUS START/STOP BITS TIMING



Note: Refer to Figure 30-5 for load conditions.

FIGURE 31-27: IDD TYPICAL, HS OSCILLATOR, PIC16LF1938/9 ONLY

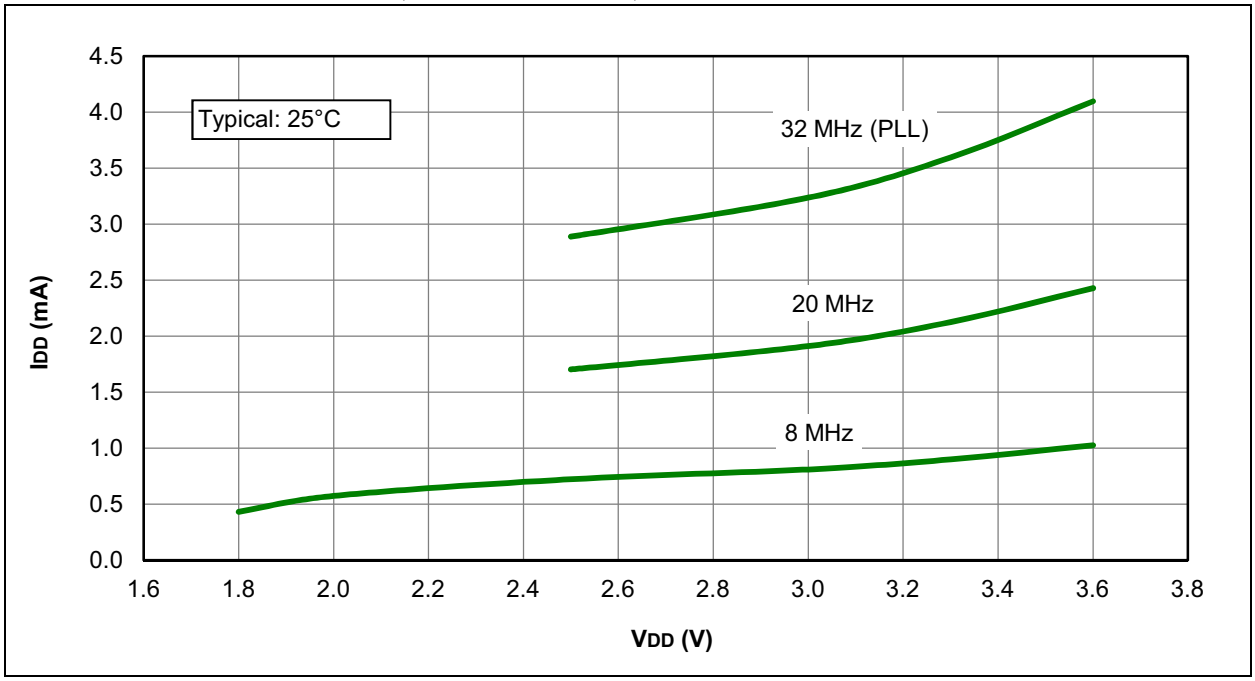
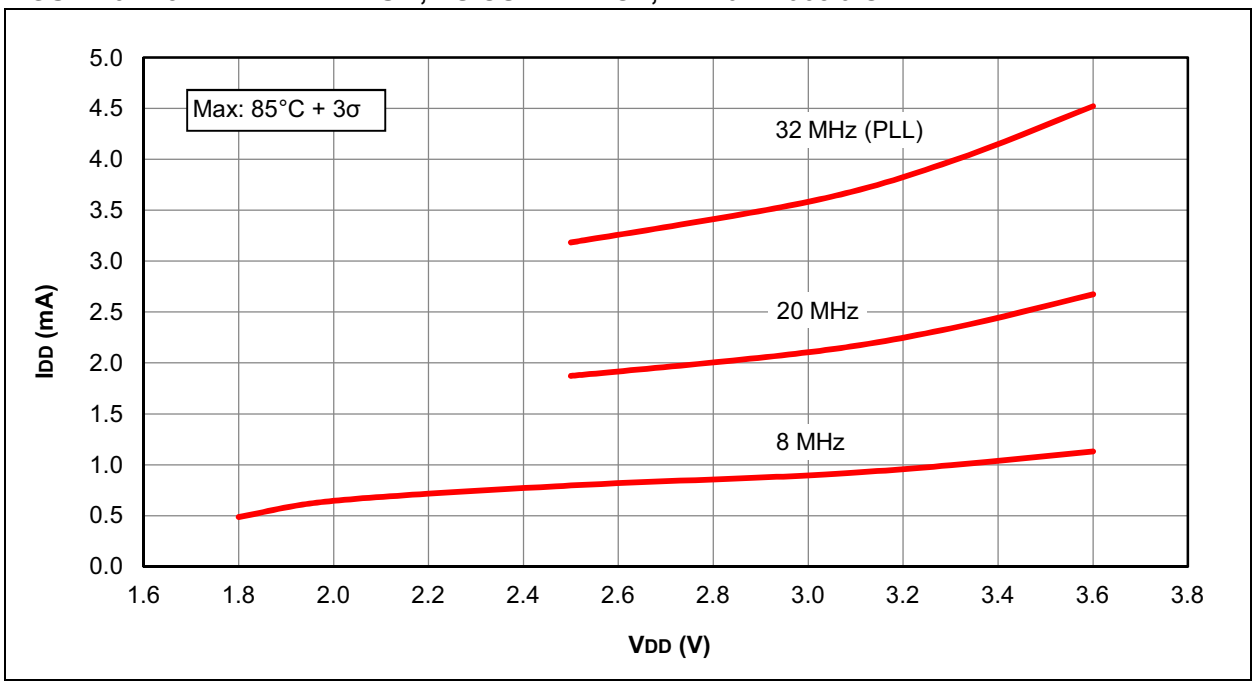
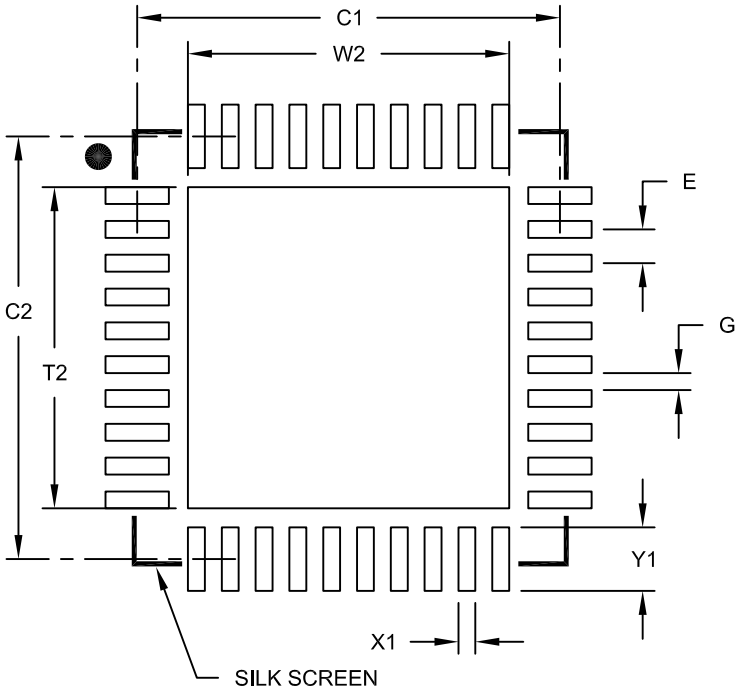


FIGURE 31-28: IDD MAXIMUM, HS OSCILLATOR, PIC16LF1938/9 ONLY



40-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) - 5x5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			3.80
Optional Center Pad Length	T2			3.80
Contact Pad Spacing	C1		5.00	
Contact Pad Spacing	C2		5.00	
Contact Pad Width (X40)	X1			0.20
Contact Pad Length (X40)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

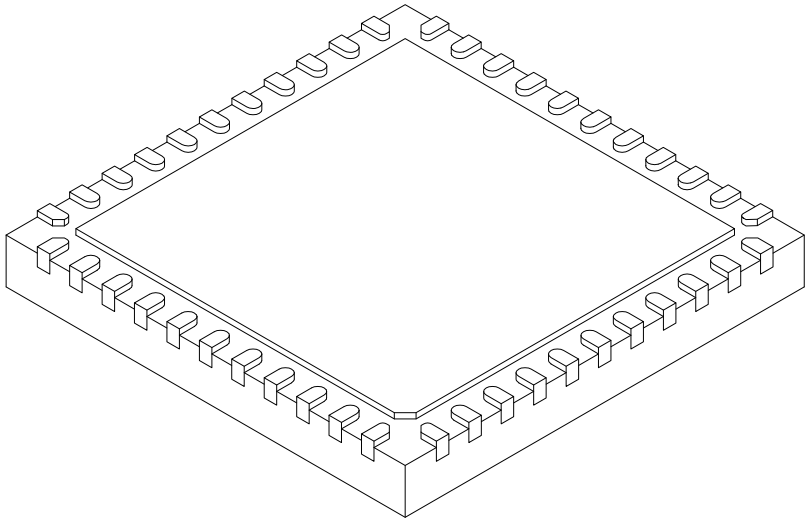
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2156B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2